

## PMP10150 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1	1	68uF	EKXG451ELL680MMN3S	Chemi-Con	CAP, AL, 68 μF, 450 V, +/- 20%, ohm, TH	D18xL31.5mm
C2, C3	2	0.22uF	B32922C3224K	EPCOS Inc	CAP, Film, 0.22 μF, 630 V, +/- 10%, TH	B32922_12.5mm
C4	1	4700pF	C3216C0G2E472J	TDK	CAP, CERM, 4700 pF, 250 V, +/- 5%, C0G/NP0, 1206	1206
C5, C6	2	270uF	EKZN250ELL271MHB5D	Chemi-Con	CAP, AL, 220 μF, 35 V, +/- 20%, 0.059 ohm, TH	D8xL15mm
C7	1	10uF	GRM31CR71C106KAC7L	MuRata	CAP, CERM, 10 μF, 16 V, +/- 10%, X7R, 1206	1206
C8	1	DNP	Used in BOM report	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	1210
C9	1		EEE-FC1V220P	Panasonic	CAP, AL, 22 µF, 35 V, +/- 20%, 1 ohm, SMD	SMT Radial D
C10	1	10uF	C3216X7R1C106M	TDK	CAP, CERM, 10 μF, 16 V, +/- 20%, X7R, 1206	1206
C11	1		EEE-FC1E220P	Panasonic	CAP, AL, 22 µF, 25 V, +/- 20%, 1 ohm, SMD	SMT Radial D
C12	1		06035A331JAT2A	AVX	CAP, CERM, 330 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C13, C15	2		C1608X7R1H473K	TDK	CAP, CERM, 0.047 µF, 50 V, +/- 10%, X7R, 0603	0603
C14	1		C0603C100J5GACTU	Kemet	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C16	1		GRM21BR71H104KA01L	MuRata	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0805	0805
C17, C18	2		C0603C101J5GAC	Kemet	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C19	1		short	TDK	CAP, CERM, 2200 pF, 250 V, +/- 20%, E, TH, 2-Leads, Body 11.5x7mm,	TH, 2-Leads, Body
					Pin Spacing 10mm	11.5x7mm, Pin
						Spacing 10mm
C20	1	3300pF	CS95ZU2GA332MYNKA	ТДК	CAP, CERM, 3300 pF, 300 V, +/- 20%, E, TH, 2-Leads, Body 11.5x7mm,	TH, 2-Leads, Body
					Pin Spacing 10mm	11.5x7mm, Pin
						Spacing 10mm
D1	1	600V	DF06S-E3	Vishay-Semiconductor	Diode, Switching-Bridge, 600 V, 1 A, DF-S	DF-S
D2	1		US1J	Diodes Inc.	Diode, Fast Rectifier, 600 V, 1 A, SMA	SMA
D3	1		10CTQ150SPBF	Used in BOM report	Diode, Schottky, xxV, xxA, [PackageReference]	Used in PnP output
23		PBF				and some BOM
		. 5.				reports
D4	1	150V	BAS20	Diodes Inc.	Diode, Switching, 150 V, 0.2 A, SOT-23	SOT-23
D5	1		MMSZ5243B-7-F	Diodes Inc.	Diode, Zener, 13 V, 500 mW, SOD-123	SOD-123
D6	1		B180-13-F	Diodes Inc.	Diode, Schottky, 80 V, 1 A, SMA	SMA
F1	1		37211250001	Littelfuse	Fuse, 1.25 A, 250 V, TH	TR5 fuse 8.5mm DIA
L1	1		7447480331	Wurth Elektronik eiSos	Inductor, Wirewound, Ferrite, 330 µH	TH, Dia 10.5mm
L2	1		744823220	Wurth Elektronik eiSos	Coupled inductor, 20 mH	13x22x17.5mm
Q1	1	201111	SPD03N60C3	Used in BOM report	MOSFET, N-CH, xxV, xxxA, DPAK	Used in PnP output
	· ·					and some BOM
						reports
R1	1	DNP	CRCW12060000Z0EA	Vishay-Dale	RES, 0, 5%, 0.25 W, 1206	1206
R2, R6, R7	3		CRCW08051M00JNEA	Vishay-Dale	RES, 1.0 M, 5%, 0.125 W, 0805	0805
R3	1	0	CRCW201068R0JNEF	Vishay-Dale	RES, 68, 5%, 0.75 W, 2010	2010
R4	1		CRCW2010200KFKEF	Vishay-Dale	RES, 200 k, 1%, 0.75 W, 2010	2010
R5	1		CRCW2010100KJNEF	Vishay-Dale	RES, 100 k, 5%, 0.75 W, 2010	2010
R8	1		CRCW080533R0JNEA	Vishay-Dale	RES, 33, 5%, 0.125 W, 0805	0805
R9, R13	2	0	CRCW08050000Z0EA	Vishay-Dale	RES, 0, 5%, 0.125 W, 0805	0805
R10	1		CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
R11	1		CRCW06035K11FKEA	Vishay-Dale	RES, 5.11 k, 1%, 0.1 W, 0603	0603
R12	1	DNP	Used in BOM report	Used in BOM report	RES, xxx ohm, x%, xW, [PackageReference]	0603
R14	1		CRCW0603215KFKEA	Vishay-Dale	RES, 215 k, 1%, 0.1 W, 0603	0603
R15	1		CRCW060349K9FKEA	Vishay-Dale	RES, 49.9 k, 1%, 0.1 W, 0603	0603
R16	1		CRCW06031K50FKEA	Vishay-Dale	RES, 1.50 k, 1%, 0.1 W, 0603	0603
	1 1	1.00K	CINO WOODS INJUI NEA	visitay-Dale	INEO, 1.00 K, 170, 0.1 ₩, 0000	10000

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
R17	1	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R18	1	45.3k	CRCW060345K3FKEA	Vishay-Dale	RES, 45.3 k, 1%, 0.1 W, 0603	0603
R19	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
R20	1	0.4	RL1206FR-070R4L	Yageo America	RES, 0.4, 1%, 0.25 W, 1206	1206
R21	1	5.76k	CRCW06035K76FKEA	Vishay-Dale	RES, 5.76 k, 1%, 0.1 W, 0603	0603
RT1	1	1 ohm	B57237S109M	EPCOS Inc	Thermistor NTC, 1 ohm, 20%, 15x7mm	15x7mm
RV1	1	275V	S10K275E2	EPCOS Inc	Varistor 275V RMS 10MM Radial, TH	10mm Radial
T1	1	300 uH	750315373	Wurth Elektronik eiSos	Transformer, 300 uH, TH	24x29.84mm
TP1, TP2, TP3, TP5	4	Double	1503-2	Keystone	Terminal, Turret, TH, Double	Keystone1503-2
TP4, TP6, TP7	3	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP8	1	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
U1	1		UCC28600D	Texas Instruments	Quasi-Resonant Flyback Green-Mode Controller with Current Control, 99 % Duty Cycle, -40 to +105 degC, 8-pin SOIC (D), Green (RoHS & no Sb/Br)	D0008A
U2	1		FOD817A	Fairchild Semiconductor	High Operating Temperature Phototransistor Optocoupler, DIP-4	DIP, 4-Leads, Body 6.86x4.83mm, Pitch 2.54mm
U3	1		LMV431AIMFX/NOPB	Texas Instruments	Low-Voltage (1.24V) Adjustable Precision Shunt Regulators, 3-pin SOT- 23, Pb-Free	MF03A

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